



FORM PTO-1449
LIST OF PATENTS AND
APPLICANT'S INFORMATION DISCLOSURE STATEMENT

ATTORNEY DOCKET NO.: 29906

SERIAL NO.: 10/091,382

FILING DATE: March 5, 2002

APPLICANT: AMMAR ET AL.

GROUP:

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIALS		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING IF APPROPRIATE
PN	AA	5,423,080	06/06/95	Perret et al.	455	90	
PN	AB	6,040,739	03/21/00	Wedeen et al.	330	66	
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						

RECEIVED
NOV 14 2002
TC 2800 MAIL ROOM

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION Yes -- No
PN	AK	0 901 181 A2	10.03.1999	EP	H01P5	08	
PN	AL	WO 02/23674 A2	21.03.2002	PCT	H01Q21	00	
	AM						

OTHER ART
(Including Author, Title, Date, Pertinent Pages, etc.)

PN	AN		Prabhu, et al., "Co-Fired Ceramic on Metal Multichip Modules for Advanced Military Packaging," Aerospace and Electronics Conference, Proceedings of the IEEE, May 24, 1993, pp. 217-222.
PN	AO		Jayaraj, et al., "RF Characterization of a Low Cost Multichip Packaging Technology For Monolithic Microwave and Millimeter Wave Integrated Circuits," Signals, Systems and Electronics, International Symposium on San Francisco, October 25, 1995, pp. 443-446.
PN	AP		Gutierrez, et al., "A Thick Film Package for Microwave ICs," Proceedings of the Electronic Component and Technology Conference, May 18, 1992, pp. 151-156.
	AQ		

EXAMINER:

Patricia Nguyen

DATE CONSIDERED:

7/10/2003

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; * Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.